


U.S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENT

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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

	<p>Yun et al., Parasitic Impedance Analysis of Double Bonding Wires for High-Frequency Integrated Circuit Packaging, IEEE Microwave and Guided Wave Letters, Vol. 5, No. 9, 296-98 (September 1995)</p>
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DATE CONSIDERED

* Copies of these references are not enclosed Pursuant to 37 CFR 1.98(d). (See accompanying IDS)